

# SOLDER CONNECTION

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## QUALITEK® Technical Bulletin

### NC600 SAC305 SOLDER WIRE

#### DESCRIPTION

A no clean flux system that is available in high melting temperature, lead-free, Sn/Ag/Cu alloys, such as SAC305 and SAC405. It provides the fluxing activity levels that promote fast wetting action and maximum wetting spread. Utilizing synthetically refined resin and very effective activator, NC600 wets and spreads like an RA type flux core. NC600 exhibits virtually no spattering and leaves minimal residue.

#### FEATURES AND BENEFITS

- Excellent wettability
- Yields clear, non-conductive residues
- RoHs compliant

#### FEATURES AND BENEFITS

Colour & Appearance	Specification	Test Method
<b>Flux Classification</b>	Light yellow opaque solid RELO	Visual J-STD-004
<b>Copper Mirror</b>	No removal of copper film	IPC-TM-650 2.3.32
<b>Silver Chromate</b>	Pass	IPC-TM-650 2.3.33
<b>Corrosion</b>	Pass	IPC-TM-650 2.6.15
<b>SIR</b> JSTD-004, Pattern Down	1.89 x 10 <sup>11</sup>	IPC-TM-650 2.6.3.3
<b>Electromigration</b>	Pass	Bellcore GR-78-CORE 13.1.4
<b>Post Reflow Flux Residue</b>	55%	TGA Analysis
<b>Acid Value (mgKOH/g)</b>	190-210	IPC-TM-650 2.3.13
<b>Flux Residue Dryness</b>	Pass	IPC-TM-650 2.4.47
<b>Spitting of Flux-Cored Solder</b>	0.3%	IPC-TM-650 2.4.48
<b>Solder Spread</b>	100 mm <sup>2</sup>	IPC-TM-650 2.4.46

#### WIRE DIAMETER

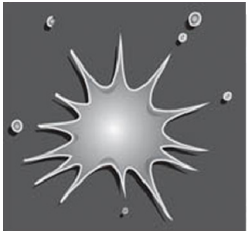
Delta Solder Wire NC600 with tin/silver copper alloys is available in a variety of diameters. The chosen diameter is based on application methods, pad size, and desired solder joint volume. Generally, the diameter of the wire should be slightly larger than the width/diameter of the joint or connection to be soldered. Below is a list of standard diameters

Diameter/Inch	0.125	0.092	0.062	0.050	0.040	0.032	0.028	0.025	0.020	0.015	0.010
Diameter/mm	3.18	2.33	1.57	1.27	1.01	0.81	0.71	0.63	0.51	0.38	0.25
Std.Wire	11	13	16	18	19	21	22	23	25	28	31
Gauge											
Tolerance, in.	+/-0.006	+/-0.005	+/-0.003	+/-0.003	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002	+/-0.002

#### FLUX PERCENTAGE

Utilizes a state-of-the-art automatic wire extrusion and wire drawing machines to manufacture consistent solder. The introduction of flux core in the wire extrusion process involves continual monitoring of flux percentage to ensure minimal flux voids and irregular wire. Typical flux percentage for high temperature lead-free SAC-containing alloy solder is 1.1 – 3.3%.

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## PHYSICAL PROPERTIES

A no clean resin based core flux with tin/silver/copper (SAC) alloys. SAC alloys conform to and exceed the impurity requirements of IPC-J-STD-006C.

## TYPICAL ANALYSIS

### Typical Analysis

	Sn	Ag	Cu	Pb	Sb	Bi	In	As	Fe	Ni	Cd	Al	Zn	Au
<b>LF955-38</b>	Bal	3.6-4.0	0.5-0.9	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
<b>LF958-35</b>	Bal	3.3-3.7	0.5-0.9	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
<b>LF965-30</b>	Bal	2.8-3.2	0.3-0.7	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max
<b>LF217</b>	Bal	3.8-4.2	0.3-0.7	0.070 Max	0.200 Max	0.100 Max	0.100 Max	0.030 Max	0.020 Max	0.010 Max	0.002 Max	0.005 Max	0.003 Max	0.050 Max

	Sn/Ag/Cu	Sn63/Pb37
Melting Point, °C	217-221	183 E
Hardness, Brinell	15HB	14HB
Coefficient of Thermal Expansion	Pure Sn= 23.5	24.7
Tensile Strength, psi	4312	4442
Density, g/cc	7.39	8.42
Electrical Resistivity , (µhm-cm)	13.0	14.5
Electrical Conductivity, %IACS	16.6	11.9

	Sn/Ag/Cu	Sn63/Pb37
Yield Strength, psi	3724	3950
Total Elongation,%	27	48
Joint Shear Strength, at 0.1mm/min 20 °C	27	23
Joint Shear Strength, at 0.1mm/min 100 °C	17	14
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 20 °C	13.0	3.3
Creep Strength, N/mm <sup>2</sup> at 0.1mm/min 100 °C	5	1
Thermal Conductivity, W/m.K	58.7	50.9

## FLUX RESIDUES & CLEANING

NC600 is a no clean formulation; therefore, residue removal is not required for typical applications. If residue removal is desired, the use of Everkleen 1005 Buffered Saponifier with a 5-15% concentration in hot 60 °C (140 °F) de-ionized water will aid in residue removal.

## STORAGE & SHELF LIFE

Solder wire storage should be in a 65-80 °F environment away from direct heat. We recommend using gloves when handling solder wire directly. Solder wire has an indefinite shelf life.

## DISPOSAL

SAC alloy NC600 lead-free solder should be disposed of in accordance with federal, state & local authority requirements.

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